



## Materials Declaration Form

<b>IPC</b>	<b>1752</b>	<b>Version</b>	<b>2</b>
<b>Form Type *</b>	<b>Distribute</b>		
<b>Sectionals *</b>	<b>Material Info</b> <b>Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2021-01-13</b>
<b>Company Unique ID</b>	<b>NL 008751171B01</b>		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>Antonella Lanzafame</b>	<b>Representative Title</b>	<b>AMS Material Declaration champion</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement		
<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>
		<b>Standard</b>

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LMV358LIDT	1DO7*V802ALL	A	BO2A	2021-01-13
	Amount	UoM	Unit type	ST ECOPACK Grade
	80.00	mg	Each	ECOPACK® 3
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	,	

Package Designator	Package Size	Nbr of instances	Shape	
DSO	4.9 x 3.9	8	Gull wing	
Comment	07 SO 08 .15 JEDEC			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description

QueryList : California Prop65 list, dated 18th December 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			true
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			false
Substance	amount in product (mg)	Application	ppm in product

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				
Query				Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				false
Hasardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
O	O	O	O	O

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

QueryList : Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Tin,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update				
Query				Response
The Product does contain at least one of the substances listed in Chemical Control Act				false
				Application Purpose

China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	
Query	Response
The product contains adhesives identified under GB 33372	true
All the adhesive impacted complies with GB 33372	true

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	1DO7*V80ZALL		80.7180		5998435.0	1008981.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.579	mg	supplier	die	Silicon(Si)	7440-21-3		0.560	mg	967185	7000
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.005	mg	8636	63
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	1727	13
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.001	mg	1727	13
				supplier	passivation	Silicon oxide	7631-86-9		0.012	mg	20725	150
Leadframe	M-004 Copper and its alloys	28.765	mg	supplier	alloy	Copper(Cu)	7440-50-8		27.987	mg	972953	349838
				supplier	alloy	Iron(Fe)	7439-89-6		0.658	mg	22875	8225
				supplier	alloy	Iron phosphide	1310-43-6		0.040	mg	1391	500
				supplier	alloy	Zinc(Zn)	7440-66-6		0.035	mg	1217	438
				supplier	metallization	Silver (Ag)	7440-22-4		0.045	mg	0	563
Die attach	M-011 Other inorganic materials	0.141	mg	supplier	glue	Silver(Ag)	7440-22-4		0.124	mg	879433	1550
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.007	mg	49645	88
				supplier	glue	Isobornyl acrylate	5888-33-5		0.007	mg	49645	88
				supplier	glue	Methyl acrylate polymer	87320-05-6		0.003	mg	21277	38
Bonding wires	M-004 Copper and its alloys	0.054	mg	supplier	wire	Copper(Cu)	7440-50-8		0.054	mg	1000000	675
Encapsulation	M-011 Other inorganic materials	50.461	mg	supplier	mold compound	Silica vitreous	60676-86-0		36.130	mg	715998	451625
				supplier	mold compound	Silicon oxide	7631-86-9		7.569	mg	149997	94613
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		3.785	mg	75008	47313
				supplier	mold compound	Phenol resin	26834-02-6		2.523	mg	49999	31538
				supplier	mold compound	Carbon black	1333-86-4		0.252	mg	4994	3150
				supplier	mold compound	Bismuth compound	7440-69-9		0.202	mg	4003	2525
Connections coating	Solder	0.718	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.718	mg	1000000	8975